



MUR860F

PINGWEI ENTERPRISE

8.0AMPS. GLASS PASSIVATED SUPER FAST RECTIFIERS

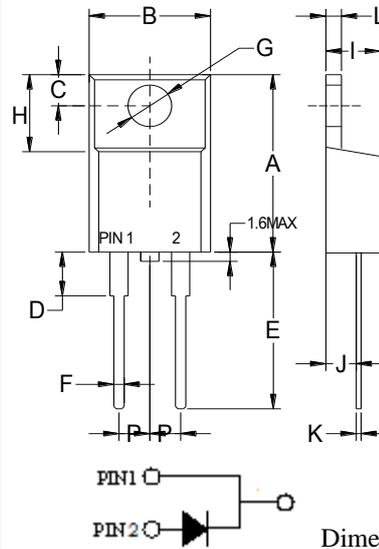
FEATURE

- . Low forward voltage drop
- . High current capability
- . High reliability
- . High surge current capability
- . Epitaxial construction
- . High temperature soldering guaranteed
260°C /10seconds, 0.25"(6.35mm)from case.

MECHANICAL DATA

- . Terminal: Plated solderable per MIL-STD 202E, method 208C
- . Case: Molded with UL-94 Class V-0 recognized Flame Retardant Epoxy
- . Polarity: color band denotes cathode
- . Mounting position: any

ITO-220AC



Dim	Min	Max
A	.571 (14.5)	.610 (15.5)
B	---	.406 (10.3)
C	.110 (2.80)	.126 (3.2)
D	---	.162 (4.1)
E	.512 (13.0)	.551 (14.0)
F	.020 (0.5)	.031 (0.78)
G	.114 (2.9)	.138 (3.5)
H	.268 (6.8)	.291 (7.4)
I	.162 (4.1)	.185 (4.7)
J	.110 (2.8)	.126 (3.2)
K	.020 (0.5)	.028 (0.7)
L	.097 (2.46)	.113 (2.86)
P	.89 (2.25)	.113 (2.85)

Dimensions in inches and (millimeters)

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Ratings at 25°C ambient temperature unless otherwise specified.

Single phase, half wave, 60Hz, resistive or inductive load.

For capacitive load, derate current by 20%

Type Number	SYMBOL	MUR860F	units
Maximum Recurrent Peak Reverse Voltage	V_{RRM}	600	V
Maximum RMS Voltage	V_{RMS}	420	V
Maximum DC blocking Voltage	V_{DC}	600	V
Maximum Average Forward Rectified Current at $T_C = 100^\circ C$	$I_{F(AV)}$	8.0	A
Peak Forward Surge Current 8.3ms single half sine- wave superimposed on rated load (JEDEC method)	I_{FSM}	120.0	A
Maximum Forward Voltage at 8.0A DC	V_F	2.3	V
Maximum DC Reverse Current @ $T_A = 25^\circ C$ at rated DC blocking voltage @ $T_A = 125^\circ C$	I_R	10.0 400.0	μA
Maximum Reverse Recovery Time (Note 1)	t_{rr}	50	ns
Typical Junction Capacitance (Note 2)	C_J	60	pF
Typical Thermal Resistance (Note 3)	$R_{(JC)}$	3.2	$^\circ C/W$
Storage Temperature	T_{STG}	-55 to +150	$^\circ C$
Operation Junction Temperature	T_J	-55 to +150	$^\circ C$

Note:

1. Test Conditions: $I_F = 8A$, $dI_F/dt = 200A/\mu s$
2. Measured at 1.0 MHz and applied reverse voltage of 4.0Vdc
3. Thermal Resistance From Junction to Case Mounted on Heatsink